

February 1, 2000

Instructions for PCB Fab. and Assy. of 3-in-1 Cards

1. The total number of boards to fabricate is 11,500 and the total number to assemble is 10,600.
2. The University of Chicago will supply all parts. The vendor is responsible for printed circuit board (PCB) fabrication, component mounting, and the preparation and mounting of cable assemblies.
3. The finished boards must conform to the Gerber files, parts lists, and mechanical drawings supplied by the University of Chicago.
4. The PCBs should be fabricated with FR4 material having a minimum transition temperature of 150°C.
5. Prior to production of any PCBs the artwork must be inspected and approved by the University of Chicago.
6. The boards may be panelized for production but the finished boards must conform to the supplied mechanical drawings and be thoroughly cleaned prior to delivery.
7. Prior to assembly, the PCBs should be 100% tested for shorts and continuity according to the supplied net list.
8. The Altera part U4 is moisture sensitive. Procedures indicated on the packaging material should be followed, including if necessary baking prior to mounting.
9. Vendor will affix self-adhesive serial number bar-code labels supplied by the University of Chicago on header J1. Serial numbers will correspond to the production sequence of the component placement process. Serial numbers, together with the date, time, machine, and operator will be logged at the start and stop of each production run and at the time of any anomaly in the production. A copy of this production log will be provided to the University of Chicago.
10. The first shipment will be 50 completed cards. These will be sent to the University of Chicago for testing and approval. Further production should be placed in a hold status until these tests are complete and satisfactory. This step will require fully-assembled cards to be at the university for 3 days.
11. Upon approval of the above sample of 50 cards, the first batch of 1000 cards may be shipped and invoiced. Each successive batch of 1000 cards may be shipped only after approval by the University of Chicago of a quality control sample of 50 cards. This sample may be drawn from the previous batch of 1000 or supplied as a special sample, at the discretion of the vendor. This cycle will continue until the total quantity is delivered.

12. Guarantee – The vendor shall be responsible for all workmanship attributes. Since the final testing will not be complete for a period of one year after delivery of the final assembly, the period of warranty shall be an equal period of one year.
13. The vendor agrees to correct workmanship errors in the assemblies that have been indicated and located by tests at the University. The corrections shall be made in 10 working days.
14. Ten percent of the contract price shall be withheld and then paid as a monthly annuity as the period of guarantee progresses. Upon completion of this period the entire contract shall be totally fulfilled.
15. Price quotations are requested within two weeks. A delay of more than three weeks will be considered a no-bid. Quotations should include price, delivery schedule, and any special conditions.
16. First delivery is requested no more than 4 weeks after receipt of components from the University of Chicago. All deliveries should be complete within 6 months from the first delivery.
17. Unused components and unassembled boards should be returned to the University of Chicago at the conclusion of the assembly work.

Shipping address:

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University of Chicago contact:

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